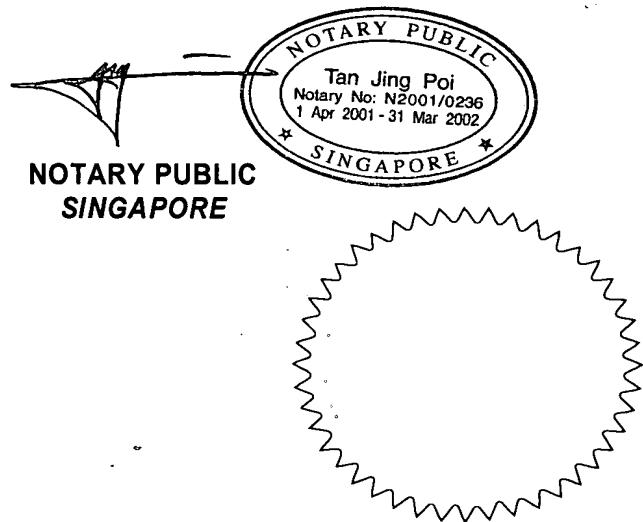




**TO ALL TO WHOM THESE PRESENTS SHALL COME**

I, TAN JING POI, NOTARY PUBLIC, duly authorised and appointed, practising in the Republic of Singapore do hereby CERTIFY AND ATTEST that I was present on the 3<sup>rd</sup> day of December 2001 and did see **LYNN TOK KWEE HOON** the person named and described in the Declaration hereto annexed and marked "LTKH-1" duly sign the same and that the name "LYNN TOK KWEE HOON" thereto subscribed is of the proper handwriting of the said **LYNN TOK KWEE HOON**.

**IN FAITH AND TESTIMONY** whereof I have hereunto subscribed my name and affixed my Seal of Office at Singapore this 3<sup>rd</sup> day of December 2001 in the Year of Our Lord Two Thousand and One (2001).



**THE OATHS AND DECLARATIONS ACT 2000**

**STATUTORY DECLARATION**

TO : COMMISSIONER OF PATENTS  
UNITED STATES PATENT AND TRADEMARK OFFICE  
WASHINGTON, D.C. 20231

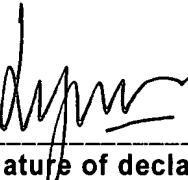
RE : U.S. PATENT APPLICATION SERIAL No. 09/845,601  
"LEADFRAME AND SEMICONDUCTOR PACKAGE MADE USING THE LEADFRAME"

I, LYNN TOK KWEE HOON, holder of Singapore National Registration and Identity Card No. S7804330/Z, care of John, Tan & Chan of 9, Battery Road, #16-08, Straits Trading Building, Singapore 049910, do solemnly and sincerely declare that :-

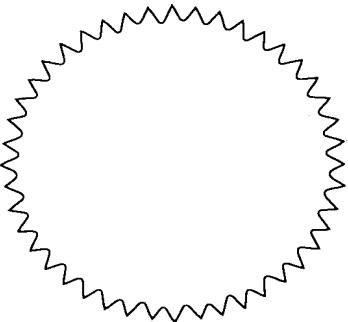
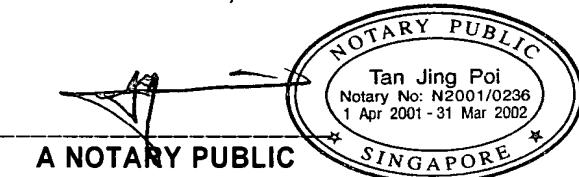
1. I, LYNN TOK KWEE HOON, an employee of John, Tan & Chan, did on November 9, 2001 personally attend at the office of Drew & Napier at 20, Raffles Place, #17-00, Ocean Towers, Singapore 048620 for the purpose of hand-delivering John, Tan & Chan's covering letter of November 9, 2001 and the following enclosures :-
  - a) U.S. Patent Application (U.S. Patent Application Serial No. 09/845,601) entitled "Leadframe and Semiconductor Package Made Using the Leadframe", including the complete specification, claims and drawings;
  - b) Declaration for Patent Application and Power of Attorney; and
  - c) Assignment.
2. Annexed hereto as "Exhibit A" is a copy of John, Tan & Chan's letter of November 9, 2001 with Drew & Napier's acknowledgement stamp.

And I make this solemn declaration by virtue of the provisions of the Oaths and Declarations Act 2000, and subject to the penalties provided by that Act for the making of false statements in statutory declarations, conscientiously believing the statements contained in this declaration to be true in every particular.

Declared at Singapore on this 3<sup>rd</sup> day of December 2001.

  
Signature of declarant

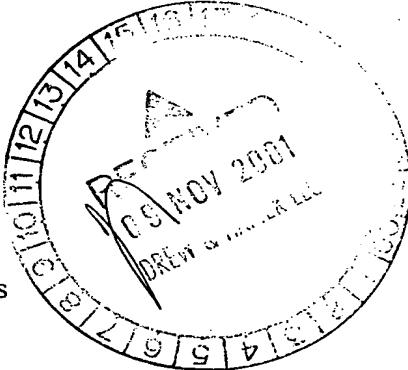
Before me,



Tan Jing Poi \*\* 陈颖培律师  
Daniel John \*\* 但以理·约翰律师  
Axel Chan \*  
  
Lim Fung Peeri 林方政律师  
Damita Nathan 邓美坦律师  
Rebecca Leong 梁碧仪律师

Your Ref: DS/JKC/sm/198092  
Our Ref: AC/aa(lt)/01060395  
Date: 9<sup>th</sup> November 2001

M/s Drew & Napier  
20 Raffles Place  
#17-00 Ocean Towers  
Singapore 048620



# John, Tan & Chan

(formerly John & Tan)

Advocates & Solicitors  
Notaries Public \*  
Commissioners for Oaths \*

9 Battery Road #16-08  
Straits Trading Building,  
Singapore 049910  
Tel: 5368266 (7 lines)  
Fax: (65) 5381882  
Email: [jontan@cyberway.com.sg](mailto:jontan@cyberway.com.sg)  
Email: [jontan@starhub.net.sg](mailto:jontan@starhub.net.sg)

WE DO NOT ACCEPT SERVICE OF  
COURT DOCUMENTS BY FAX

*By fax (533 0694) & by hand  
(Enclosures by hand only)*

Attn : Davinder Singh, Esq./Jupiter Kong, Esq.

Dear Sirs,

**Re: U.S. Patent Application entitled:**  
**“Leadframe And Semiconductor Package Made Using The Leadframe”**  
**U.S. Application serial no: 09/845,601**  
**Inventors:** Byung Hoon Ahn, Jae Hun Ku, Young Suk Chung,  
Suk Gu Ko, Sung Sik Jang, Young Nam Choi  
& Won Chul Do  
**Filing date:** 26<sup>th</sup> April 2001

We have been instructed to seek the assistance of Messrs. Byung Hoon Ahn and Jae Hun Ku of ST Assembly and Test Services (“STATS”) in the above U.S. patent application filed by our clients, Amkor Technology, Inc.

The above application – in which Messrs. Byung Hoon Ahn and Jae Hun Ku are two of the named inventors – is based on 3 Korean Patent Applications filed on 27<sup>th</sup> April 2000, 20<sup>th</sup> July 2000 and 25<sup>th</sup> October 2000, respectively.

Enclosed herewith are the following :-

- a) U.S. Patent Application entitled “Leadframe And Semiconductor Package Made Using The Leadframe”, including the complete specification, claims and drawings;
- b) Declaration for Patent Application and Power of Attorney (“the Declaration”); and
- c) Assignment.

Kindly forward the above enclosures to Messrs. Byung Hoon Ahn and Jae Hun Ku for their review and signatures, and return the same to us by 23<sup>rd</sup> November 2001. Please fill in the addresses of Messrs. Byung Hoon Ahn and Jae Hun Ku in the Declaration.

*John, Tan & Chan*

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To : M/s Drew & Napier  
Date : 9<sup>th</sup> November 2001  
Ref : AC/aa(lt)/01060395

- 2 -

Finally, please let us know if Messrs. Byung Hoon Ahn and Jae Hun Ku are aware of any prior art that is material to the patentability of the invention so that our clients may disclose it to the U.S. Patent Office.

If Messrs. Byung Hoon Ahn and Jae Hun Ku will not cooperate, or if STATS will not allow them to cooperate, please let us know immediately.

Yours faithfully,  
for *John, Tan & Chan*

  
Axel Chan  
Encl.

cc clients